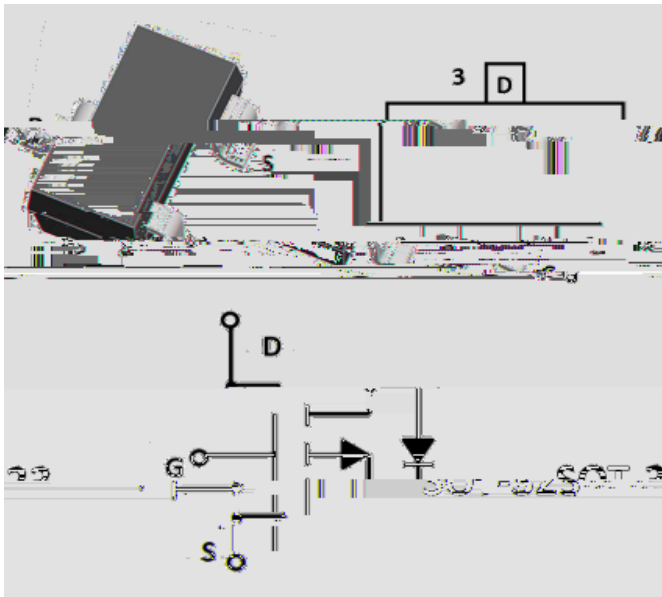


P-Channel Enhancement Mode Field Effect Transistor



Product Summary

I_D	-1.2 A
$R_{DS(ON)}$ (at $V_{GS} = 1.8V$)	130 mohm
$R_{DS(ON)}$ (at $V_{GS} = -2.5V$)	170 mohm
$R_{DS(ON)}$ (at $V_{GS} = -1.8V$)	250 mohm

General Description

- Trench Power LV MOSFET technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Part no. with suffix "Q" means AEC-Q101 qualified

Applications

- Video monitor
- Power management

Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-source Voltage	V_{DS}	-20	V
Gate-source Voltage	V_{GS}	± 10	V
Drain Current T7	I_D	$T_A = 25^\circ C$ @ Steady State	-1.2
		$T_A = 70^\circ C$ @ Steady State	-1.0
Pulsed Drain Current ^A	I_{DM}	-9.6	A
≤ 1 A			
Thermal Resistance Junction-to-Ambient ^B	R_{JA}	400	/W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 +150	

Ordering Information

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJL2101WQ	F2	TS1.	3000	30000	120000	7" reel



YJL2101WQ

Electrical Characteristics ($T_J=25$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-20V, V_{GS}=0V, T_A=25$			-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 10V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.3	-0.6	-1.0	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-4.5V, I_D=-1.5A$		100	130	m
		$V_{GS}=-2.5V, I_D=-1.2A$		135	170	
		$V_{GS}=-1.8V, I_D=-1.0A$		180	250	
Diode Forward Voltage	V_{SD}	$I_S=-2.0A, V_{GS}=0V$		-0.9	-1.2	V
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{DS}=-10V, V_{GS}=0V, f=1MHz$		210		pF
Output Capacitance	C_{oss}			37		
Reverse Transfer Capacitance	C_{rss}			30		
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=-4.5V, V_{DS}=-10V, I_D=-1.2A$		2.9		nC
Gate Source Charge	Q_{gs}			0.65		
Gate Drain Charge	Q_{gd}			0.7		
Reverse Recovery Charge	Q_{rr}	$I_{SD}=-1.2A, di/dt=60A/us$		0.9		nC
Reverse Recovery Time	t_{rr}			5.4		ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=-4.5V, V_{DS}=-10V, I_D=-1.2A, R_g=3$		4.8		ns
Turn-on Rise Time	t_r			22		
Turn-off Delay Time	$t_{D(off)}$			21		
Turn-off Fall Time	t_f			28		

A. Repetitive rating; pulse width limited by max. junction temperature.

B. Device mounted on FR-4 PCB, 1 mm x 17mm x 15mm.

v 7\SLFDO 3HUIRUPDQFH &KDUDFWHULVWLFV

)LJXUH 2XWSXW &KDUDFWHULVWLFV)LJXUH 7UDQVIHU &KDU

)LJXUH &DSDFLWDQFH &KDUDFWHULVWLFV)LJXUH *DWH &KDU

)LJXUH 2Q 5HVLVWVDFRFXUFHDWRHOWDJH)LJXUH 1 7•00



Figure 7. $R_{DS(on)}$ VS Drain Current

Figure 8. Forward characteristics of reverse diode

Figure 9. Normalized breakdown voltage

Figure 10. Normalized Threshold voltage

